VALVE ELECTRONIC CV2389

GENERAL POST OFFICE: E-IN-C (S)

Specification: G.P.O./CV 2389/Issue 3

Dated: 1st July, 1957

To be read in conjunction with K 1001

Specification
Unclassified

Unclassified

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TYPE OF VALVE: - Germanium Junction Transisto PROTOTYPES CXT, P.O. No. 2	MARKING- CV 2389 and, if possible - the Factory Code and Date Code - see K1001/4. The Collector lead shall be indicated by a white spot on the body adjacent to the lead.					
RATINGS	Note	The emitter and base leads shall be indicated by spacing in an approved manner as				
Max. mean (Vcb) Max. peak collector to emitter voltage (Vce)	65 55 0.4 10 10 10 7 10 7 10	A B	shown on Page 4. Dimensions (mm) Dimension Min. Max. Diameter - 7 Length of body - 16 Lead diameter 0.34 0.48 Lead length 30 -			
Max. mean (Vce) Average Noise Factor	7 5 5 12	B C	BODY The Body shall be insulated from all leads or alternatively shall be covered with an approved insulating sleeve.			
A:- Freely suspended in still air a pressure.	MOUNTING POSITION Any					
B:- These are for guidance in linear with inductive loads. C:- Measured in a common emitter ci - 2V and Ic = - 0.5 mA. Source impedance 500 ohms Load impednace 2500 ohms to Frequency 1000 cps Temperature 25°C	PACKAGING K 1005 Individual container; Carton Group A. OR packaging shall be in accordance with K 1005, Section 8 except that protection against R.F.fields is not necessary.					

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TV 2389

To be performed in addition to those applicable in K1001.

The transistors are to be subjected to the Dry Heat Conditioning of Test (a) before being tested to the remainder of the Test Schedule.

		AQL	AQL Insp. Level		Limits		
Test					Min.	Max.	Unit
Dry Heat Conditioning	Six cycles of dry heat in accordance with BS 2011 clause 4.7 except that the humidity requirement is optional.		100%		,		
Glass Strain Test and Damp Heat	K1001 clause 7.1 except that water at a temperature of 14-17°C shall be used instead of ice-cold water. The same sample shall then undergo six cycles to BS 2011 clause 4.7 (including the humidity requirements)		100% or S (K1001 6.2 and 6.1)				
Post Conditioning Tests	Test (e) Test (f) Test (g)						
Lead Fragility	Transistors used for this test shall have undergone the damp heat conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz.	6.5	IA				• • •
Soldering	Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. The Test is to be in accordance with BS 2011, clause 4.4 and is to be carried out between 6mm and 30mm from the body of the transistor. A thermal sink is to be used between the body of the transistor and the point of soldering.	6.5	IA				
	Conditioning Class Strain Test and Damp Heat Post Conditioning Tests Lead Fragility	Dry Heat Conditioning Six cycles of dry heat in accordance with BS 2011 clause 4.7 except that the humidity requirement is optional. K1001 clause 7.1 except that the humidity requirement is optional. K1001 clause 7.1 except that that water at a temperature of 14-17°C shall be used instead of ice-cold water. The same sample shall then undergo six cycles to BS 2011 clause 4.7 (including the humidity requirements) Post Conditioning Tests Test (e) Test (g) Lead Transistors used for this test shall have undergone the damp heat conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz. Soldering Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. The Test is to be in accordance with BS 2011, clause 4.4 and is to be carried out between 6mm and 30mm from the body of the transistor. A thermal sink is to be used between the body of the transistor and the	Dry Heat Conditioning Six cycles of dry heat in accordance with BS 2011 clause 4.7 except that the humidity requirement is optional. K1001 clause 7.1 except that that water at a temperature of 14-17°C shall be used instead of ice-cold water. The same sample shall then undergo six cycles to BS 2011 clause 4.7 (including the humidity requirements) Post Conditioning Test (e) Test (g) Lead Transistors used for this test shall have undergone the damp heat conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz. Soldering Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. The Test is to be in accordance with BS 2011, clause 4.4 and is to be carried out between 6mm and 30mm from the body of the transistor. A thermal sink is to be used between the body of the transistor and the	Dry Heat Conditioning Conditi	Dry Heat Conditioning Six cycles of dry heat in accordance with BS 2011 clause 4.7 except that the humidity requirement is optional. Glass Strain Test and Damp Heat K1001 clause 7.1 except that that water at a temperature of 14-17°C shall be used instead of ice-cold water. The same sample shall then undergo six cycles to BS 2011 clause 4.7 (including the humidity requirements) Post Conditioning Test (e) Test (f) Test (g) Lead Transistors used for this test shall have undergone the damp heat conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz. Soldering Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz. Soldering Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. The Test is to be in accordance with BS 2011, clause 4.4 and is to be carried out between 6mm and 30mm from the body of the transistor. A thermal sink is to be used between the body of the transistor and the	Dry Heat Conditioning Six cycles of dry heat in accordance with BS 2011 clause 4.7 except that the humidity requirement is optional. K1001 clause 7.1 except that the humidity requirement is optional. K1001 clause 7.1 except that the humidity requirement is optional. K1001 clause 7.1 except that the humidity requirement is optional. K1001 clause 7.1 except that the same sample shall then undergo six cycles to BS 2011 clause 4.7 (including the humidity requirements) Fost Conditioning Test (e) Test (f) Test (g) Lead Transistors used for this test shall have undergone the damp heat conditioning of Test (b) above once. K1001 / 5.12 except that the weight shall be 8 oz. Soldering Transistors used for this test shall have undergone the damp heat Conditioning of Test (b) above once. The Test is to be in accordance with BS 2011, clause 4.4 and is to be carried out between 6mm and 30mm from the body of the transistor. A thermal sink is to be used between the body of the transistor and the	Dry Heat Conditioning Class Strain Test and Damp Heat Class Strain Test and Damp Heat Conditioning Class Strain Test and Damp Heat Conditioning Class Strain Test and Damp Heat Conditioning C

	Test	Test Conditions	AQL %	Insp. Level		Limits		Unit
	, 1050					Min.	Max.	
(e)	Collector-Base Cut-off current	Vcb = - 4.5V Ie = 0		100%	Icbo		10	, ALA
(f)	Collector- emitter cut-off current	Vce = - 10V Tb = 0	1 111	100%	Iceo		0.5	m A
(g)	Common emitter current gain	Vce = - 2V Ic = - 1mA d.c. and not greater than 0.25mA r.m.s. a.c. Frequency not greater than 1000 c/s.		100%	hfe (∝ob)	30	70	
(h)	Collector- emitter Voltage	Ib = - 0.5 mA Ic = - 10 mA	2.5	I	Vce		0.25	v
(j)	Base-emitter Voltage	Tb = - 0.5 mA Vce = - 1V	2.5	I	Vbe		0.5	v
(k)	Noise Factor	Common emitter circuit Voe = - 2V. Ic = - 0.5mA. Source impedance 500 chms Load impedance 2500 chms to 10K.Frequency 1000c/s	6.5	I	N		18	đb
(m)	Common-base Cut-off frequency	Vcb = - 2V. Ic = - 1 mA dc (See Note 3).	2.5	I	fox	350		ko/s
(n)	Illumination effect. Change in Collector - Base Cut-off Current.	As in test e. 100W clear tungsten lamp at a distance of 18" from the transistor under test in any direction.	2.5	I	∆ Іово		1	μA

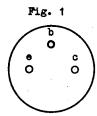
CV 2389/3/3

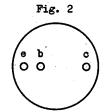
NOTES

- The sign convention for all currents is positive into the named electrode and for voltages is positive on the first electrode named.
- All Test limits refer to an ambient temperature of 25°C (BS 2725:1956). Correction factors for other temperatures are to be agreed with the Inspection Authorities.
- 3. The fx is the frequency at which the current gain in the common base configuration drops to .707 of its value at 1000 c/s.
- 4. The Test limits denote Magnitude without regard to sign.

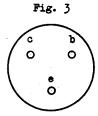
LEAD DISPOSITION

(as viewed from the wired end)





Where an anticlockwise connexions of leads (i.e. Fig 3) is used the Transistors shall be marked CVX



CV 2389/3/4